

IGBT

Features

- 650V,40A
- V_{CE(sat)(typ.)}=1.8V@V_{GE}=15V,I_C=40A
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms
- Square RBSOA

General Description

JIAEN FS IGBTs offer lower losses and higher energy efficiency for application such as IH (induction heating), UPS, general inverter and other soft switching applications.

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
Vces	Collector-Emitter Voltage	650	V
Vges	Gate-Emitter Voltage	<u>+</u> 30	V
lc	Continuous Collector Current (Tc=25 $^\circ\!\mathrm{C}$)	80	A
	Continuous Collector Current (Tc=100 $^{\circ}$ C)	40	A
Ісм	Pulsed Collector Current (Note 1)	120	A
IF	Diode Continuous Forward Current ($T_C=100$ $^\circ\!C$)	40	A
lfм	Diode Maximum Forward Current (Note 1)	120	A
t _{sc}	Short Circuit Withstand Time	5	us
	Maximum Power Dissipation (T_c=25 $^\circ\!\!\!\mathrm{C}$)	246	W
PD	Maximum Power Dissipation ($T_{C}\text{=}100^{\circ}\text{C}\text{)}$	123	W
TJ	Operating Junction Temperature Range	-45 to +175	°C
Tstg	Storage Temperature Range	-55 to +150	°C

Thermal Characteristics

Symbol	Parameter	Max.	Units
Rth j-c	Thermal Resistance, Junction to case for IGBT	0.61	°C/W
R _{th j-c}	Thermal Resistance, Junction to case for Diode	1.15	°C/ W
R _{th} j-a	Rth j-a Thermal Resistance, Junction to Ambient		°C/W

Symbol 2.Collector 1.Gate 3.Emitter



Electrical Characteristics (Tc=25 $^{\circ}$ C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV _{CES}	Collector-Emitter Breakdown Voltage	V _{GE} = 0V, I _C = 250uA	650	-	-	V
I _{CES}	Collector-Emitter Leakage Current	V _{CE} = 650V, V _{GE} = 0V	-	-	100	uA
I _{GES}	Gate Leakage Current, Forward	$V_{GE} = + 20V, V_{CE} = 0V$	-	-	<u>+</u> 100	nA
V _{GE(th)}	Gate Threshold Voltage	$V_{GE} = V_{CE}, I_C = 250 \text{uA}$	4.0	-	5.6	V
V _{CE(sat)}	Collector-Emitter Saturation Voltage	V _{GE} =15V, I _C = 40A	-	1.8	2.4	V
Qg	Total Gate Charge	Vcc=480V V _{GE} =15V Ic=40A	-	88.8		nC
Qge	Gate-Emitter Charge		-	16.3		nC
Qgc	Gate-Collector Charge		-	50.8		nC
t d(on)	Turn-on Delay Time	$V_{CC}=400V$ $V_{GE}=15V$ $I_{C}=40A$ $R_{G}=15\Omega$ Inductive Load $T_{C}=25\ ^{\circ}C$	-	34	-	ns
t r	Turn-on Rise Time		-	60	-	ns
t d(off)	Turn-off Delay Time		-	138	-	ns
t f	Turn-off Fall Time		-	34	-	ns
Eon	Turn-on Switching Loss		-	1.3	-	mJ
Eoff	Turn-off Switching Loss		-	0.6	-	mJ
Ets	Total Switching Loss		-	1.9	-	mJ
Cies	Input Capacitance	- V _{CE} =25V V _{GE} =0V f = 1MHz	-	2050	-	pF
Coes	Output Capacitance		-	104	-	pF
Cres	Reverse Transfer Capacitance		-	32	-	pF

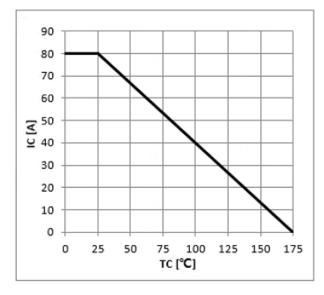
Electrical Characteristics of Diode (Tc=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V _F	Diode Forward Voltage	I _F =40A	-	1.5	2.3	V
trr	Diode Reverse Recovery Time	V _{CE} = 400V	-	110		ns
l r r	Diode peak Reverse Recovery Current	I _F = 40A	-	19.4		А
Qr r	Diode Reverse Recovery Charge	Rg=15 Ω	-	1186		nC

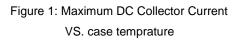
Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature





Typical Performance Characteristics



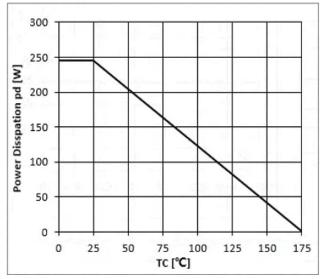


Figure 2: Power Dissipation VS. Case Temperature

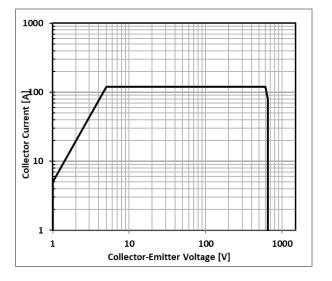


Figure 3: Reverse Bias SOA,TJ=125 $^\circ\!\mathrm{C}$,VGE=15V

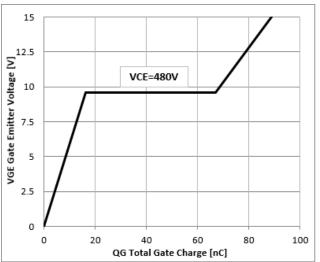
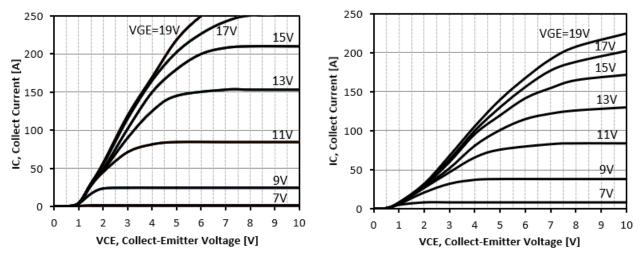
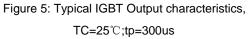
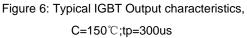


Figure 4: Typical Gate charge VS. VGE,IC=40A









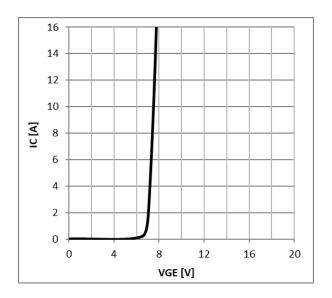


Figure 7: Typical Gate Threshold Voltage

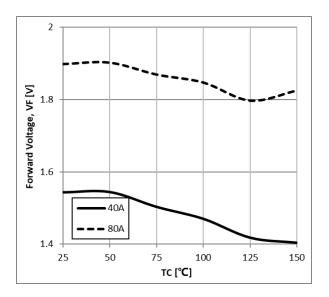


Figure 8: Typical Forward Voltage vs IF



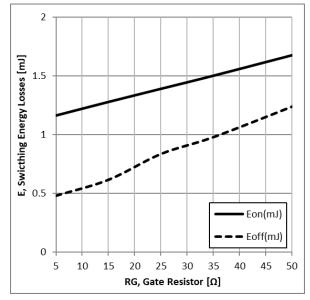


Figure 9: Typical Energy Loss VS. RG, TC=25℃, L=200uH,VCE=400V,VGE=15V,IC=40A

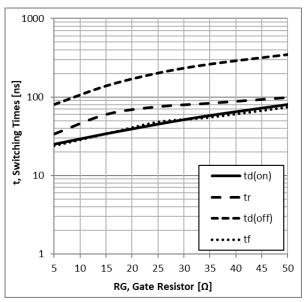


Figure 10: Typical Switching Time VS. RG, TC=25 $^\circ C$, L=200uH,VCE=400V,VGE=15V,IC=40A

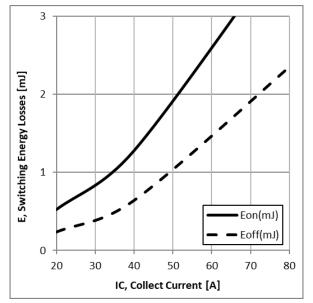
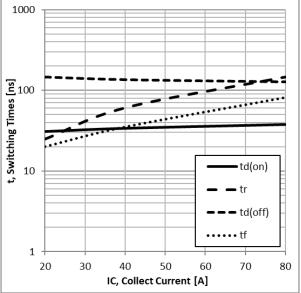
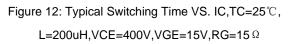


Figure 11: Typical Energy Loss VS. IC,TC=25°C, L=200uH, VCE=400V, VGE=15V,RG=15 Ω







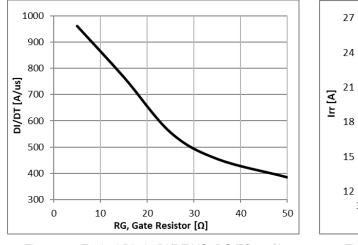
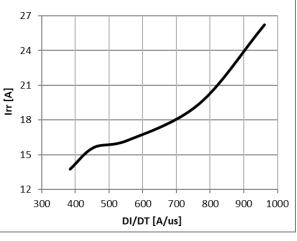
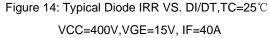
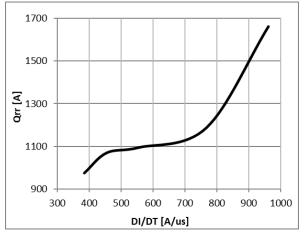
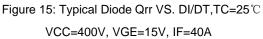


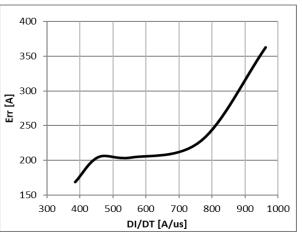
Figure 13: Typical Diode DI/DT VS. RG,TC=25°C VCC=400V, VGE=15V, IF=40A

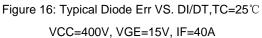




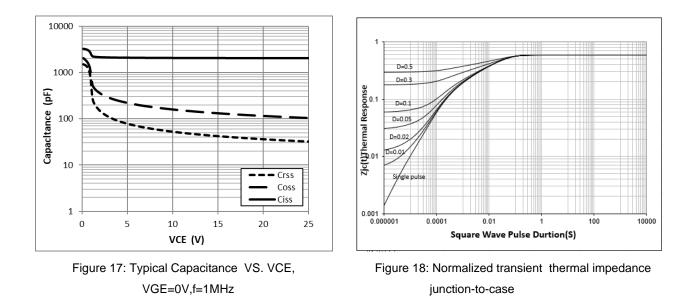






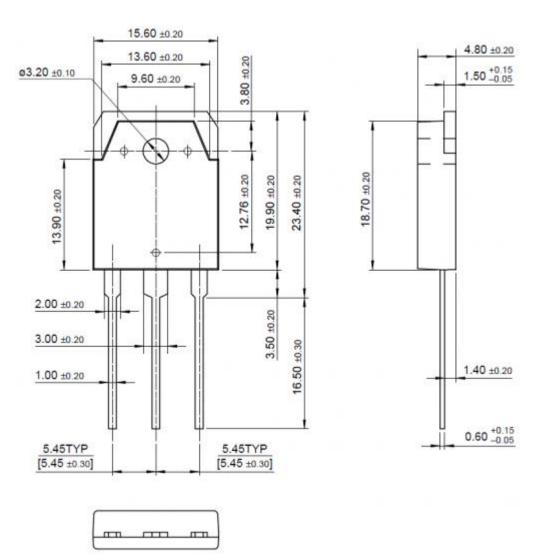








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